

In the Specification:

Replace the first paragraph on page 1, lines 2- 6 with the following paragraph.

A
This application is a continuation-in-part of USSN U.S. Patent Application Serial No. 09/387,084, filed 08/31/1999, titled "Methods and Apparatus for Controlling and/or Measuring Additive Concentration in an Electroplating Bath" (now issued as U.S. Patent No. 6,356,033), which is a continuation of PCT/US99/09659, filed 05/03/1999 and published in English under PCT Article 21(2), titled "Methods and Apparatus for Controlling and/or Measuring Additive Concentration in an Electroplating Bath", which claims priority from U.S. Provisional Patent Application Serial No. 60/083,882, filed May 1, 1998, entitled "Closed Loop Electrolyte Composition Monitoring and Control System for Copper Interconnect Applications". both of which The disclosures of these applications are incorporated herein by reference in their entireties.